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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/777,976	02/06/2001	Wesley M. Enroth	EN9-98-072US2	3360
5409 7:	590 11/19/2003		EXAMINER	
ARLEN L. OLSEN SCHMEISER, OLSEN & WATTS 3 LEAR JET LANE SUITE 201 LATHAM, NY 12110			CHANG, RICK KILTAE	
			ART UNIT	PAPER NUMBER
			3729	, to the second
			DATE MAILED: 11/19/2003	13

Please find below and/or attached an Office communication concerning this application or proceeding.

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· · · · · · · · · · · · · · · · · · ·		Application No.	Applicant(s)			
Office Action Summary		09/777,976	ENROTH ET AL.			
		Examiner	Art Unit			
		Rick K. Chang	3729			
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply						
A SH THE I - External after - If the - If NO - Failu - Any rearne Status	ORTENED STATUTORY PERIOD FOR REPL' MAILING DATE OF THIS COMMUNICATION. nsions of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. reperiod for reply specified above is less than thirty (30) days, a reply period for reply is specified above, the maximum statutory period v ire to reply within the set or extended period for reply will, by statute reply received by the Office later than three months after the mailing and patient term adjustment. See 37 CFR 1.704(b). Responsive to communication(s) filed on 23 Si	36(a). In no event, however, may a reply be ting within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE and this communication, even if timely filed	nely filed /s will be considered timely. It the mailing date of this communication. ED (35 U.S.C. § 133).			
·		_				
<u> </u>	This action is FINAL . 2b) This action is non-final. Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4)⊠	4)⊠ Claim(s) <u>1,5,6,8,10,12,13,15,16 and 21-28</u> is/are pending in the application.					
	4a) Of the above claim(s) is/are withdraw	wn from consideration.				
5)	5) Claim(s) is/are allowed.					
6)🖂	Claim(s) <u>1,5,6,8,10,12,13,15,16 and 21-28</u> is/are rejected.					
7)	Claim(s) is/are objected to.					
	Claim(s) are subject to restriction and/o	r election requirement.				
Applicati	ion Papers	•				
9) The specification is objected to by the Examiner.						
10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
Priority under 35 U.S.C. §§ 119 and 120						
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).						
a)[* S 13)	All b) Some * c) None of: 1. Certified copies of the priority documents: 2. Certified copies of the priority documents: 3. Copies of the certified copies of the priority application from the International Bureau See the attached detailed Office action for a list acknowledgment is made of a claim for domestifince a specific reference was included in the first 7 CFR 1.78. Comparison of the foreign language provides the comparison of the foreign language provides the comparison of the first sentence of the comparison of the comparison of the first sentence of the comparison	s have been received. s have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)). of the certified copies not receive c priority under 35 U.S.C. § 119(e st sentence of the specification or evisional application has been rec c priority under 35 U.S.C. §§ 120	ion No ed in this National Stage ed. e) (to a provisional application) r in an Application Data Sheet. ceived. and/or 121 since a specific			
Attachment(s) 1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413) Paper No(s)						
2) 🔲 Notic	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of Informal P	Patent Application (PTO-152)			

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1 and 21-23 are rejected under 35 U.S.C. 102(b) as being anticipated by.

Amago discloses in Fig. 12 with a solder resist 107 provided on the bottom of the PCB to obstruct molten solder. 2 is a conductive lining and 5 is cured.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 5-6, 8, 10, and 24-28 are rejected under 35 U.S.C. 103(a) as being unpatentable over Amago et al (US 5,402,314) in view of Majd (US 5,155,904).

Amago discloses placing and fixing top and bottom components (Fig. 2), lining an interior wall of the via (2), Fig. 9 shows 2 at the end of the bottom surface.

Amago fails to disclose wave soldering and providing leaded components.

Majd discloses wave soldering (Fig. 1) and providing leaded and PIH components (44, 46, 53, 54 and 55).

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It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Amago by wave soldering and providing leaded and PIH components, as taught by Majd, for the purpose of increasing production by mass soldering IC components.

5. Claims 12-13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sabotke et al (US 5,737,834) in view of Nakaso et al (US 5,638,598), and further in view of Lauffer et al (US 5,867,898).

Sabotke discloses in Fig. 1 steps of applying solder paste, reflow soldering components, and fixing a second component onto the PCB. In light of the claimed invention, Sabotke's components mounted on the top surface will be the bottom components mounted in the claimed invention, and vice versa.

Sabotke fails to disclose providing a PCB having a soldered via electrically communicating between layers as well as top to bottom layers and screen printing solder.

Nakaso discloses in Fig. 3 a solder plug in a via formed in a PCB.

Lauffer discloses in claim 8 screening the solder paste.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Sabotke by providing a PCB having a soldered via electrically communicating between layers as well as top to bottom layers and screen printing solder, as taught by Nakaso and Lauffer, for the purpose of allowing forming densenly formed contacts to electrically communicate between layers and top and bottom surfaces, as well as increase production by mass soldering a plurality of vias and pads.

It is inherent that when a solder mass is reflowed, the solder mass in the via will be melted and reformed and redistributed.

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6. Claims 15-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sabotke et al (US 5,737,834)/Nakaso et al (US 5,638,598)/Lauffer et al (US 5,867,898) as applied to claims 12-13 above, and further in view of Majd (US 5,155,904) and Thompson, Jr. (US 5,704,535).

Sabotke/Nakaso/Lauffer fail to mount PIH components and wave soldering with shielding.

Thompson discloses shielding the board during wave soldering (Fig. 1).

Madj discloses mounting PIH components in Fig.s 8-9.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Sabotke/Nakaso/Lauffer by mounting PIH components and shielding the board during wave soldering, as taught by Madi and Thompson, for the purpose of performing desired

operation and protecting the sensitive parts of the board.

Response to Arguments

7. Applicant's arguments filed 9/23/03 have been fully considered but they are not persuasive.

Fig. 12 shows 107 forms a plug in the via 105.

104 is mounted on the top surface of 102 and 107 obstructs flow of the molten solder into the via during soldering.

Sabotke discloses in Fig. 1 steps of applying solder paste, reflow soldering components, and fixing a second component onto the PCB. In light of the claimed invention, Sabotke's components mounted on the top surface will be the bottom components mounted in the claimed invention, and vice versa. Sabotke fails to disclose providing a PCB having a soldered via electrically communicating between layers as well as top to bottom layers and screen printing

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solder. Nakaso discloses in Fig. 3 a solder plug in a via formed in a PCB. Lauffer discloses in claim 8 screening the solder paste. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Sabotke by providing a PCB having a soldered via electrically communicating between layers as well as top to bottom layers and screen printing solder, as taught by Nakaso and Lauffer, for the purpose of allowing forming densenly formed contacts to electrically communicate between layers and top and bottom surfaces, as well as increase production by mass soldering a plurality of vias and pads.

Interviews After Final

8. Applicant note that an interview after a final rejection must be submitted briefly in writing the intended purpose and content of the interview (the agenda of the interview must be in writing). Upon review of the agenda, the Examiner may grant the interview if the examiner is convinced that disposal or clarification for appeal may be accomplished with only nominal further consideration. Interviews merely to restate arguments of record or to discuss new limitations will be denied. See MPEP 714.13 and 713.09.

Conclusion

9. Please provide reference numerals (either in parentheses next to the claimed limitation or in a table format with one column listing the claimed limitation and another column listing corresponding reference numerals in the remark section of the response to the Office Action) to all the claimed limitations as well as support in the disclosure for better clarity. Applicants are duly reminded that a full and proper response to this Office Action that includes any amendment to the claims and specification of the application as

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originally filed requires that the applicant point out the support for any amendment made to the disclosure, including the claims. See 37 CFR 1.111 and MPEP 2163.06.

10. THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

11. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Rick K. Chang whose telephone number is (703) 308-4784. The examiner can normally be reached on 5:30 AM to 1:30 PM, Monday through Thursday.

The fax phone numbers for the organization where this application or proceeding is assigned are (703) 872-9302 for regular communications and (703) 872-9303 for After Final communications.

RICHARD CHANG PRIMARY EXAMINER Page 6